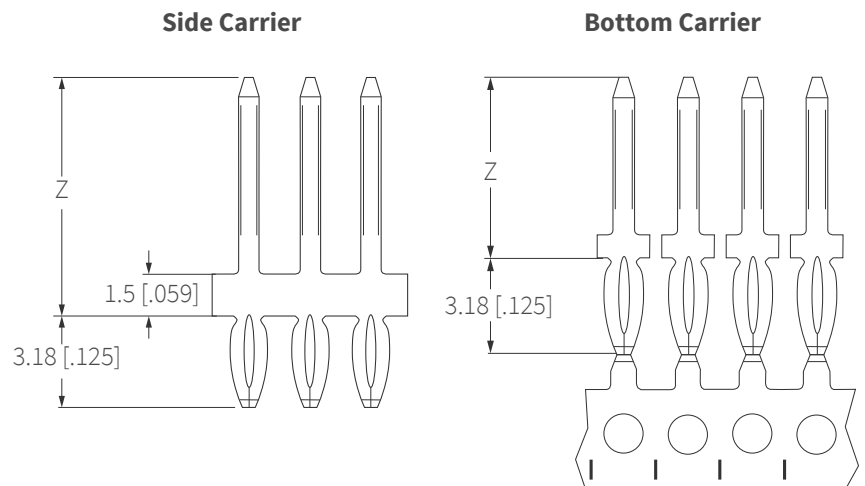


1.5 BLADE PRESS-FIT TERMINAL SPECIFICATIONS

TYPE	PART NUMBER	MATERIAL	SIZE	Z LENGTH		PCB HOLE SIZE	CARRIER TYPE	CURRENT CAPACITY STANDARD	CURRENT CAPACITY HI-TEMP
				MM	INCH				
1.5 Blade	7-V5005-135TT	Standard	1.5 x .81	13.60	0.535	B	Side Carrier	15 A	30 A
	7-V5005-015AA	Standard	1.5 x .81	13.90	0.547	B	Side Carrier	15 A	30 A
	7-V5005-025AA	Standard	1.5 x .82	19.40	0.764	B	Side Carrier	15 A	30 A
	7-V5017-015TT	Standard	1.5 x .81	15.40	0.606	B	Side Carrier	15 A	30 A
	7-V5017-025TT	Standard	1.5 x .82	25.60	1.008	B	Side Carrier	15 A	30 A
	7-V5017-035TT	Standard	1.5 x .81	11.50	0.453	B	Side Carrier	16 A	32 A
	7-V5064-005TT	Standard	1.5 x .81	15.34	0.604	B	Bottom Carrier	15 A	30 A

NOTE:

- Current Carrying Capacity (Current Rating) for $\Delta T = 30^{\circ}\text{C}$ Heat Rise
- Current Carrying Capacity (Current Rating) for C42520 is defined per: SAE/USCAR-2 - Revision 5 - Section 5.3.3, EIA Publication 364 - Procedure 70 thru the testing
- Current Carrying Capacities (Current Rating) for C19010 are defined using C42520 data and theoretical formula
- All current ratings must be verified during validation testing of the final assembly



PRESS-FIT PCB HOLE SIZE REQUIREMENTS

HOLE SIZE	COMPONENT THICKNESS	FINISHED HOLE DIAMETER	DESCRIPTION	PC BOARD DIMENSIONS
B	0.81 mm	1.50 mm	Drilled Hole	1.60 ± 0.025 mm
			Copper Plating	
			Plating Thickness	25 μm min
			Hole Diameter	1.50 ± 0.05 mm
			Finished Hole	
			Tin Plating Thickness	2 μm-8 μm
			Plated Hole Diameter	1.50 ± 0.05 mm
			Precious metal Plated (Note 2)	1.50 ± 0.05 mm

NOTE:

1. Tin thickness applies to tin-lead and lead free plating.

2. Precious metal plating types:

Immersion Au:

0.08 μm-0.13 μm [3 μin-5 μin] Gold over
3.8 μm-7.6 μm [150 μin-300 μin] Nickel

Immersion Ag:

0.2 μm-0.5 μm [8 μin -20 μin]